



### **General Description**

The MAX9633 is a low-noise, low-distortion operational amplifier that is optimized to drive ADCs for use in applications from DC to a few MHz. The MAX9633 features low noise (3nV/ $\sqrt{\rm Hz}$  at 1kHz and 3.5nV/ $\sqrt{\rm Hz}$  at 100Hz) and low distortion (130dB at 10kHz), making it suitable for industrial, medical, and test applications.

The exceptionally fast settling-time and low input offset voltage makes the IC an excellent solution to drive high-resolution 12-bit to 18-bit SAR ADCs.

The IC operates from a wide supply voltage range up to 36V with only 3.5mA of guiescent current per amplifier.

The IC is offered in an 8-pin, 3mm x 3mm TDFN package for operation over the -40°C to +125°C temperature range.

### **Applications**

**ADC Drivers** 

Data Acquisition and Instrumentation

Power Grid Systems

Motor Control

Test and Measurement Equipments

**Imaging Systems** 

High-Performance Audio Circuitry

#### **Features**

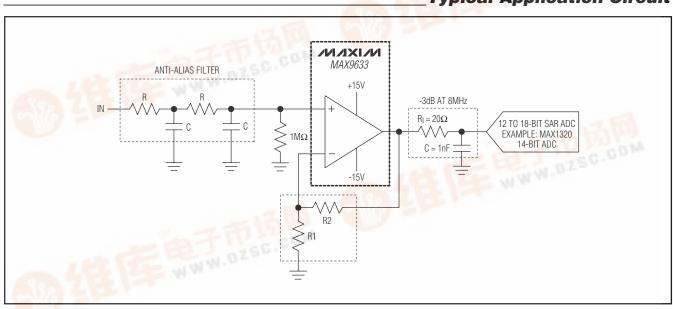
- ◆ Low-Noise (3nV/√Hz at 1kHz) and Low-Distortion (130dB at 10kHz) ADC Driver
- ♦ Very Fast 750ns Settling Time to 16-Bit Accuracy
- ◆ Low Input Voltage Offset 200µV (max)
- ◆ Low 0.9µV/°C Input Offset Temperature Coefficient
- ♦ Gain-Bandwidth Product 27MHz
- ◆ 4.5V to 36V Wide Supply Range
- **◆ Unity Gain Stable**
- ♦ ±6kV ESD Protection HBM
- ♦ 8-Pin, 3mm x 3mm TDFN Package

## **Ordering Information**

PART	TEMP RANGE	PIN-PACKAGE
MAX9633ATA+	-40°C to +125°C	8 TDFN-EP*

<sup>+</sup>Denotes a lead(Pb)-free/RoHS-compliant package.

## **Typical Application Circuit**



<sup>\*</sup>EP = Exposed pad.

#### **ABSOLUTE MAXIMUM RATINGS**

Supply Voltage (VCC to VEE)0.3V to +40V	Package Thermal Resistance (Note 1)
All Other Pins(VEE - 0.3V) to (VCC + 0.3V)	θJA42°C/W
Short-Circuit Duration of OUTA, OUTB	θJC8°C/W
Continuous Input Current (any pins)±20mA	Operating Temperature Range40°C to +125°C
Continuous Power Dissipation (T <sub>A</sub> = +70°C)	Junction Temperature+150°C
TDFN (derate 24.4mW/°C above +70°C)	Storage Temperature Range65°C to +150°C
Multilayer Board1904.8mW	Soldering Temperature (reflow)+260°C

**Note 1:** Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, refer to **www.maxim-ic.com/thermal-tutorial**.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### **ELECTRICAL CHARACTERISTICS**

 $(V_{CC} = +15V, V_{EE} = -15V, V_{CM} = 0V, R_L = 10k\Omega$  to  $V_{GND} = 0V, T_A = T_{MIN}$  to  $T_{MAX}$ , unless otherwise noted. Typical values are at  $T_A = +25^{\circ}C$ .) (Note 2)

PARAMETER	SYMBOL	CON	DITIONS	MIN	TYP	MAX	UNITS
POWER SUPPLY	1	1		I.		<del>_</del>	1
Supply Voltage Range	VCC - VEE	Guaranteed by PSR	4.5		36	V	
			T <sub>A</sub> = +25°C		3.5	5	
Supply Current	Icc	Per amplifier	-40°C ≤ T <sub>A</sub> ≤ +85°C			6	mA
			$-40$ °C $\leq$ T <sub>A</sub> $\leq$ $+125$ °C			6.5	
Power-Supply Rejection Ratio	er-Supply Rejection Ratio PSRR +4.5		T <sub>A</sub> = +25°C	112	135		dB
Tower-oupply Rejection Ratio	1 01111	≤+36V	-40°C ≤ T <sub>A</sub> ≤ +125°C	110			] ub
DC SPECIFICATIONS							
Input Offset Voltage	Vos	T <sub>A</sub> = +25°C	$T_A = +25^{\circ}C$		±70	±200	μV
mput Onset Voltage	705	-40°C ≤ TA ≤ +125°C				±290	μν
Input Offset Voltage Drift (Note 3)	ΔVos	-40°C ≤ TA ≤ +125°C		0.2	0.9	μV/°C	
1	1_	$(VEE + 0.45V) \le VCM \le (VCC - 1.8V)$			±42	±400	nA
Input Bias Current	IB	VEE ≤ VCM ≤ (VCC -	1.8V)		4.5	22	μΑ
Input Offset Current	loo	(VEE + 0.45V) ≤ VCN	n ≤ (VCC - 1.8V)		±30	±300	nA
Input Offset Current	los	VEE ≤ VCM ≤ (VCC -	1.8V)		±200	±2000	I IIA
Input Valtage Dange	Van Van	Currenteed by CMI	T <sub>A</sub> = +25°C	VEE		V <sub>C</sub> C - 1.7	V
Input Voltage Range	VIN+, VIN-	Guaranteed by CMF	-40°C ≤ TA ≤ +125°C	VEE		V <sub>CC</sub> -	V
		VEE ≤ VCM ≤ (VCC -	1.7V), T <sub>A</sub> = +25°C	106	130		
Common-Mode Rejection Ratio	CMRR	VEE ≤ V <sub>CM</sub> ≤ (V <sub>CC</sub> - 1.8V), -40°C ≤ T <sub>A</sub> ≤ +125°C		105	130		dB
Open Lean Cain	A. (O.)	(VEE + 0.3V) ≤ VOUT 5	$\leq$ (VCC - 2V), RL = $10$ k $\Omega$	118	140		
Open-Loop Gain Avoi		$(V_{EE} + 0.45V) \le V_{OUT} \le (V_{CC} - 2.1V), R_L = 1k\Omega$		115	138		dB

### **ELECTRICAL CHARACTERISTICS (continued)**

 $(VCC = +15V, VEE = -15V, VCM = 0V, R_L = 10k\Omega$  to VGND = 0V, TA = TMIN to TMAX, unless otherwise noted. Typical values are at TA = +25°C.) (Note 2)

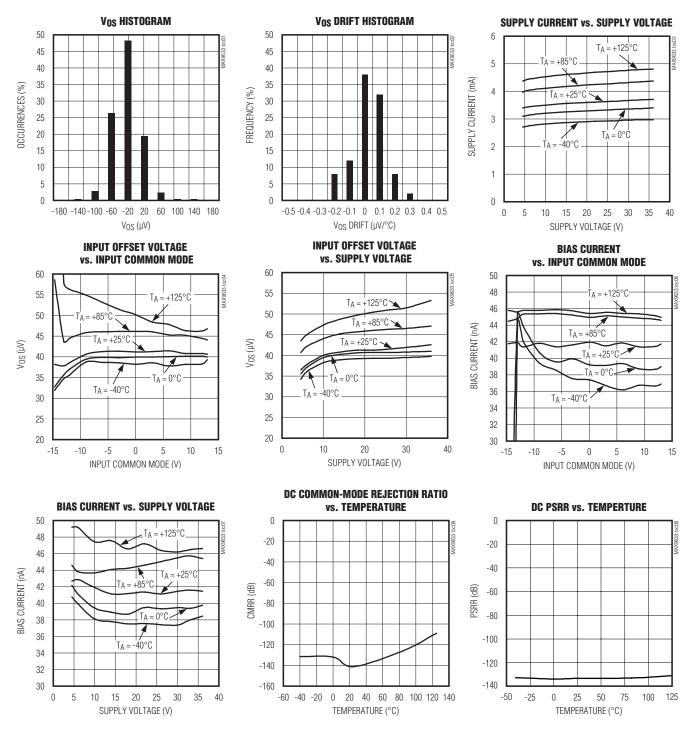
PARAMETER	SYMBOL	CONDIT	IONS	MIN	TYP	MAX	UNITS	
	\/a	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	$R_L = 10k\Omega$		1.6	1.9	V	
	Voн	VCC - VOUT	$R_L = 1k\Omega$		1.7	2.0		
Output Valtage Swing			$R_L = 10k\Omega$		70	150	mV	
Output Voltage Swing	VOL	\/a \/	$R_L = 1k\Omega$		170	300		
	VOL	VOUT - VEE	$R_L = 10k\Omega$ to $V_{EE}$		20	100		
			$R_L = 1k\Omega$ to VEE		20	100		
Short-Circuit Current	Isc	T <sub>A</sub> = +25°C			50		mA	
AC SPECIFICATIONS								
Gain Bandwidth	GBWP				27		MHz	
Slew Rate	SR	5V step, Rs = $20\Omega$ , CL	= 1nF, A <sub>V</sub> = 1V/V		18		V/µs	
Output Transient Recovery Time	tTR	To 0.001%, $\Delta$ VOUT = 20 = 1nF, AV = +1V/V		500		ns		
	ts	To 0.001%, 5V step, AV = -1V/V	$R_S = 100\Omega$ , $C_L = 30pF$		750			
Settling Time			$R_S = 20\Omega$ , $C_L = 1$ nF		750		ns	
		Vout = 10V <sub>P-P</sub> , Rs =	f = 1kHz		145		dB	
Total Harmonic Distortion	THD	$20\Omega$ , CL = 1nF, Ay =	f = 10kHz		130			
		+1V/V	f = 100kHz		-100		1	
Crantally		Vout = 10V <sub>P-P</sub> , Rs =	f = 1kHz		-100		٩D	
Crosstalk		$20\Omega$ , C <sub>L</sub> = 1nF	f = 10kHz		-90	-	dB	
Input Valtage Naige Density		f = 100Hz			3.5		\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	
Input Voltage Noise Density	en	f = 1kHz			3		nV/√Hz	
Input Voltage Noise		$0.1Hz \le f \le 10Hz$			250		nV <sub>P-P</sub>	
Input Current Noise Density	:	f = 100Hz			12		pA√Hz	
Input Current Noise Density	in	f = 1kHz			10			
Capacitive Loading	CL	No sustained oscillation, A <sub>V</sub> = +1V/V			50		pF	

Note 2: All devices are 100% production tested at  $T_A = +25^{\circ}C$ . Temperature limits are guaranteed by design.

Note 3: Guaranteed by design.

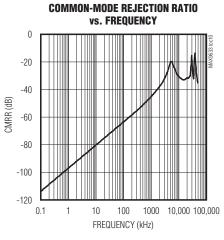
## **Typical Operating Characteristics**

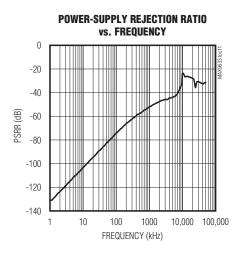
 $(V_{CC} = +15V, V_{EE} = -15V, V_{CM} = 0V, outputs have R_L = 10k\Omega$  connected to GND = 0V. Typical values are at T\_A = +25°C, unless otherwise noted.)

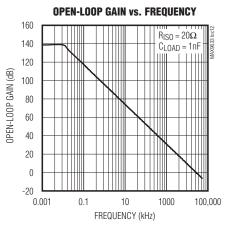


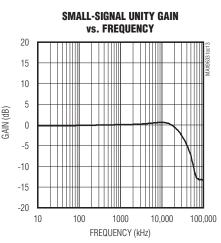
## Typical Operating Characteristics (continued)

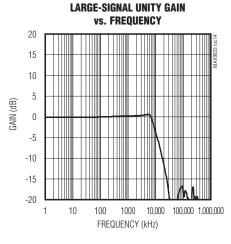
 $(V_{CC} = +15V, V_{EE} = -15V, V_{CM} = 0V, outputs have R_L = 10k\Omega$  connected to GND = 0V. Typical values are at  $T_A = +25^{\circ}C$ , unless otherwise noted.)

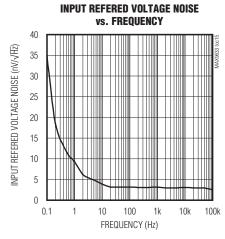


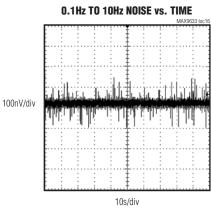


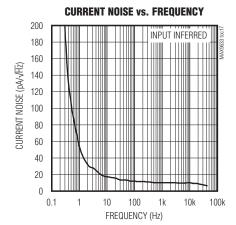








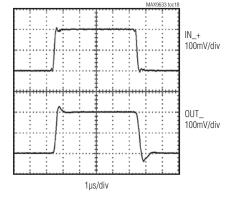




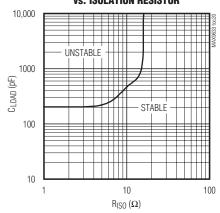
## Typical Operating Characteristics (continued)

 $(V_{CC} = +15V, V_{EE} = -15V, V_{CM} = 0V, outputs have R_L = 10k\Omega$  connected to GND = 0V. Typical values are at T\_A = +25°C, unless otherwise noted.)

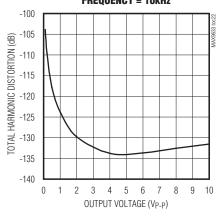
#### **SMALL-SIGNAL STEP RESPONSE vs. TIME**



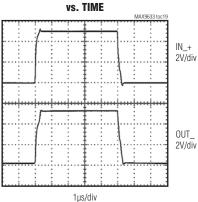
# CAPACITIVE LOAD vs. ISOLATION RESISTOR



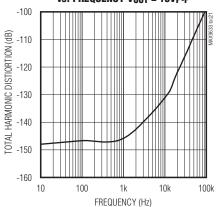
# THD vs. OUTPUT VOLTAGE FREQUENCY = 10kHz



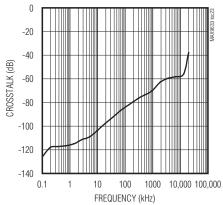
## LARGE-SIGNAL STEP RESPONSE



# TOTAL HARMONIC DISTORTION vs. FREQUENCY Vout = 10Vp-p



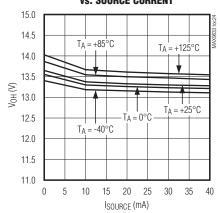
#### CROSSTALK vs. FREQUENCY



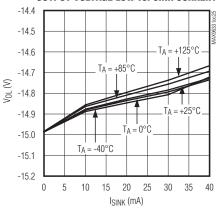
## Typical Operating Characteristics (continued)

 $(V_{CC} = +15V, V_{EE} = -15V, V_{CM} = 0V, outputs have R_L = 10k\Omega$  connected to GND = 0V. Typical values are at T\_A = +25°C, unless otherwise noted.)

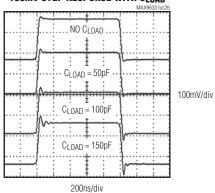




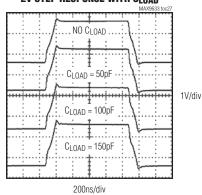
#### **OUTPUT VOLTAGE LOW vs. SINK CURRENT**



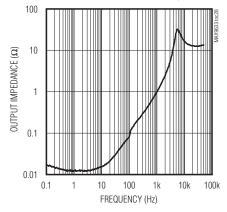
#### 100mV STEP RESPONSE WITH CLOAD



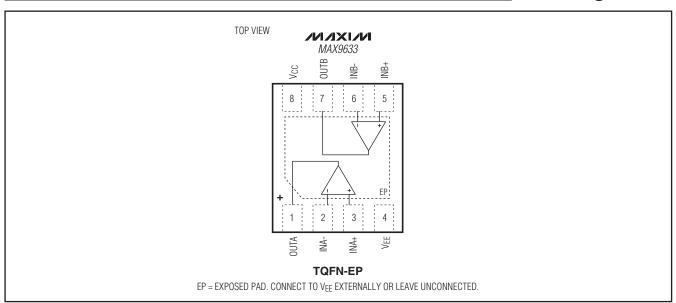
#### 2V STEP RESPONSE WITH CLOAD



#### **OUTPUT IMPEDANCE vs. FREQUENCY**



# **Pin Configuration**



# **Pin Description**

PIN	NAME	FUNCTION			
1	OUTA	Output A			
2	INA-	Negative Input A			
3	INA+	Positive Input A			
4	VEE	Negative Supply Voltage. Bypass with a 0.1µF capacitor to ground.			
5	INB+	Positive Input B			
6	INB-	legative Input B			
7	OUTB	Output B			
8	Vcc	ositive Supply Voltage. Bypass with a 0.1µF capacitor to ground.			
_	EP	Exposed Pad. Connect to VEE externally or leave unconnected.			

\_/N/XI/N

## **Detailed Description**

The MAX9633 is designed in a new 36V, high-speed complementary BiCMOS process that is optimized for excellent AC dynamic performance combined with high-voltage operation.

The exceptionally fast settling time, low noise, low distortion, high bandwidth, and low input offset voltage make the IC an excellent solution to drive (up to 18-bit)high-resolution and fast SAR ADCs.

The MAX9633 is unity gain stable and operates either with a single supply voltage up to 36V or with dual supplies up to  $\pm 18V$ .

## Applications Information

#### **Driving High-Resolution SAR ADCs**

High-resolution SAR ADCs typically switch an input capacitor in the order of tens of pF during the track and hold phases. Such capacitor switching can cause a voltage glitch at the input of the ADC that behaves as a load-transient condition for the driving amplifier. In many applications, this glitch is avoided by placing an external capacitor at the ADC input that is in the order of 20 to 50 times the ADC input capacitor. If the ADC input capacitor ranges from 15pF to 30pF, then the external capacitor is anything between 300pF to 1.5nF, depending on the application. An isolation resistor can be placed in series between the amplifier's output and the external capacitor, as shown in the *Typical Application Circuit*.

During the load-transient condition described, the driving amplifier must be able to settle to  $0.5 \times LSB$  within the ADC acquisition time (tACQ). Assuming a first order approximation, the number of time constants required to settle to  $0.5 \times LSB$  is a logarithm function of the number N of bits:

$$k = ln(2^{N+1})$$

The external RC time constant must be such that: 2)  $k \times RL \times C < tACQ$ 

As an example, consider a 16-bit SAR ADC with 500ns acquisition time and 20pF input capacitor.

From 1): k = 12

Assuming a factor of 50 for the external capacitor:

C = 1nF

Finally, formula 2) gives:  $RL \le 40\Omega$ 

The IC is optimized for very fast load-transient recovery with big capacitive loads and small isolation resistors.

This makes it ideal to drive high-resolution and fast SAR ADCs.

#### **Recommended SAR ADCs**

The MAX9633's wide supply range and fast settling make it ideal for driving high-resolution SAR ADCs, such as the MAX1320. The MAX1320 is a 14-bit, 8-channel, simultaneous-sampling ADC that measures analog inputs up to  $\pm 5V$ . Sampling up to 250ksps per channel for eight channels, the MAX1320 achieves 77dB SNR, 90dBc SFDR, and -86dB THD. The MAX1320's fast sample rate and typical input resistance of  $8.6k\Omega$  often make it necessary to have a low-noise op amp, such as the MAX9633, driving its inputs. The MAX9633 is also a good fit for an anti-aliasing active filter prior to the MAX1320 as shown in the *Typical Application Circuit*.

The MAX1320 is part of a family of simultaneous sampling ADCs (MAX1316–MAX1326). Other options include ADCs that measure 0V to 5V inputs, or  $\pm 10$ V inputs, and two 4 or 8 simultaneous input channels. The MAX1320's high speed and resolution make it a fit for multiphase motor control and power-grid monitoring.

The MAX9633 is also well-suited to drive the 16-bit MAX11046 8-channel, simultaneous-sampling, SAR ADC. The MAX11046 is rated for up to 250ksps. An input driver is typically not necessary at sampling rates below 100ksps. For applications that require > 100ksps sample rates, the MAX9633 offers small size, high bandwidth, and ultra-low -100dB THD at 100kHz.

#### **Low Noise and Low Distortion**

The MAX9633 is designed for applications that require very low voltage noise, making it ideal for low source impedance. When driving 16-bit SAR ADCs with a ±5V full-scale input, such as the MAX11046, the MAX9633 very low input voltage noise density specification guarantees 16-bit resolution up to 10MHz of signal bandwidth.

The MAX9633 is also designed for ultra-low distortion performance. THD specifications in the *Electrical Characteristics* and *Typical Operating Characteristics* is calculated up to the 5th harmonic. Even when driving high voltage swing up to 10VP-P, the MAX9633 maintains excellent low distortion operation up and beyond 100kHz of bandwidth.

Besides driving high-resolution and high-bandwidth SAR ADCs, applications that benefit for low-noise and low-distortion applications can be found in industrial powergrid and smart-grid, industrial motor-control, medical imaging, automated test equipment, instrumentation, and professional audio equipment.

#### **Input Common Mode and Output Swing**

The IC's input common-mode range as well as the output range can swing to the negative rail VEE. These two features are very important for applications where the MAX9633 is used with a single supply (VEE connected to ground). In such a case, being able to swing the input common-mode to the negative rail offers ground-sensing capability.

#### **Input Differential Voltage Protection**

During normal op-amp operation, the inverting and non-inverting inputs of the IC are at essentially the same voltage. However, either due to fast input voltage transients or due to other fault conditions, these pins can be forced to be at two different voltages.

Internal back-to-back diodes protect the inputs from an excessive differential voltage (Figure 1). Therefore, IN+ and IN- can be any voltage within the range shown in the *Absolute Maximum Ratings*. Note the protection time is still dependent on the package thermal limits.

If the input signal is fast enough to create the internal diode's forward bias condition (0.7), the input signal current must be limited to 20mA or less. If the input signal current is not inherently limited, an external input series resistor can be used to limit the signal input current. Care should be taken in choosing the input series resistor value, since it degrades the low-noise performance of the device.

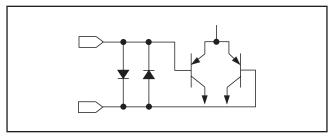


Figure 1. Input Protection Circuit

#### Electrostatic Discharge (ESD)

The IC has built-in circuits to protect from electrostatic discharge (ESD) events. An ESD event produces a short, high-voltage pulse that is transformed into a short current pulse once it discharges through the device. The built-in protection circuit provides a current path around the op amp that prevents it from being damaged. The energy absorbed by the protection circuit is dissipated as heat. ESD protection is guaranteed up to 6kV with the Human Body Model (HBM).

The Human Body Model simulates the ESD phenomenon wherein a charged body directly transfers its accumulated electrostatic charge to the ESD-sensitive device. A common example of this phenomenon is when a person accumulates static charge by walking across a carpet and then transfers all of the charge to an ESD-sensitive device by touching it.

#### **Power Supplies and Layout**

The IC can operate with dual supplies from  $\pm 2.25 \text{V}$  to  $\pm 18 \text{V}$  or with a single supply from  $\pm 4.5 \text{V}$  to  $\pm 36 \text{V}$  with respect to ground. When used with dual supplies, bypass both VCC and VEE with their own  $0.1 \mu\text{F}$  capacitor to ground. When used with a single supply, bypass VCC with a  $0.1 \mu\text{F}$  capacitor to ground. Careful layout technique helps optimize performance by decreasing the amount of stray capacitance at the op amp's inputs and outputs. To decrease stray capacitance, minimize trace lengths by placing external components close to the op amp's pins.

For high-frequency designs, ground vias are critical to provide a ground return path for high-frequency signals and should be placed around the signal traces and near the decoupling capacitors. Signal routing should be short and direct to avoid parasitic effects. Avoid using right angle connectors since they may introduce a capacitive discontinuity and ultimately limit the frequency response.

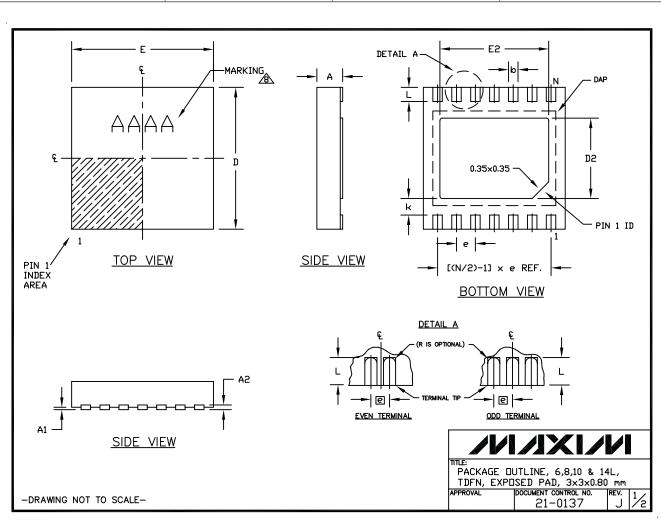
Chip Information

PROCESS: BICMOS

## Package Information

For the latest package outline information and land patterns, go to <a href="www.maxim-ic.com/packages">www.maxim-ic.com/packages</a>. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

PACKAGE TYPE	PACKAGE CODE	OUTLINE NO.	LAND PATTERN NO.
8 TDFN-EP	T833+3	<u>21-0137</u>	90-0058



### Package Information (continued)

For the latest package outline information and land patterns, go to <a href="https://www.maxim-ic.com/packages">www.maxim-ic.com/packages</a>. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

COMMON DIMENSIONS						
SYMBOL	MIN.	MAX.				
Α	0.70	0.80				
D	2.90	3.10				
Е	2.90	3.10				
A1	0.00	0.05				
L	0.20	0.40				
k	0.25 MIN.					
A2	A2 0.20 REF.					

PACKAGE V	PACKAGE VARIATIONS							
PKG. CODE	N	D2	E2	е	JEDEC SPEC	b	[(N/2)-1] x e	
T633-2	6	1.50±0.10	2.30±0.10	0.95 BSC	MO229 / WEEA	0.40±0.05	1.90 REF	
T833-2	8	1.50±0.10	2.30±0.10	0.65 BSC	MO229 / WEEC	0.30±0.05	1.95 REF	
T833-3	8	1.50±0.10	2.30±0.10	0.65 BSC	MO229 / WEEC	0.30±0.05	1.95 REF	
T1033-1	10	1.50±0.10	2.30±0.10	0.50 BSC	MO229 / WEED-3	0.25±0.05	2.00 REF	
T1033MK-1	10	1.50±0.10	2.30±0.10	0.50 BSC	MO229 / WEED-3	0.25±0.05	2.00 REF	
T1033-2	10	1.50±0.10	2.30±0.10	0.50 BSC	MO229 / WEED-3	0.25±0.05	2.00 REF	
T1433-1	14	1.70±0.10	2.30±0.10	0.40 BSC		0.20±0.05	2.40 REF	
T1433-2	14	1.70±0.10	2.30±0.10	0.40 BSC		0.20±0.05	2.40 REF	
T1433-3F	14	1.70±0.10	2.30±0.10	0.40 BSC		0.20±0.05	2.40 REF	

#### NOTES:

- 1. ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES.
- 2. COPLANARITY SHALL NOT EXCEED 0.08 mm.
- 3. WARPAGE SHALL NOT EXCEED 0.10 mm.
- 4. PACKAGE LENGTH/PACKAGE WIDTH ARE CONSIDERED AS SPECIAL CHARACTERISTIC(S).
- 5. DRAWING CONFORMS TO JEDEC MO229, EXCEPT DIMENSIONS "D2" AND "E2", AND T1433-1 & T1433-2.
- 6. "N" IS THE TOTAL NUMBER OF LEADS.
- 7. NUMBER OF LEADS SHOWN ARE FOR REFERENCE ONLY.
- A MARKING IS FOR PACKAGE ORIENTATION REFERENCE ONLY.
- 9. ALL DIMENSIONS APPLY TO BOTH LEADED (-) AND PHFREE (+) PKG. CODES.

21-0137

THE:
PACKAGE DUTLINE, 6,8,10 & 14L,
TDFN, EXPOSED PAD, 3×3×0.80 mm
PPROVAL | DOCUMENT CONTROL NO. | REV.

-DRAWING NOT TO SCALE-

# **Revision History**

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	9/10	Initial release	_

Maxim cannot assume responsibility for use of any circuitry other than circuitry entirely embodied in a Maxim product. No circuit patent licenses are implied. Maxim reserves the right to change the circuitry and specifications without notice at any time.